

Establishing the Quality Assurance Programme for the Strip Sensor Production of the ATLAS Tracker Upgrade Including Irradiation with Neutrons, Photons and Protons to HL-LHC Fluences

I. Kopsalis^{1*}, P. Allport¹, E. Bach⁷, A. Bhardwaj⁸, A. Chisholm¹, V. Cindro², V. Fadeyev³, P. Federicova⁴, J. Fernandez-Tejero^{5,6}, C. Fleta⁷, P. Freeman¹, W. George¹, J. Glover¹, L. Gonella¹, K. Hara¹¹, S. Hirose¹¹, A. Hunter¹, T. Ishii¹¹, T. Knight⁸, J. Kroll⁴, J. Kvasnicka⁴, C. Lacasta⁹, V. Latonova⁴, J. Lomas¹, I. Mandić², M. Mikestikova⁴, K. Nakamura¹¹, R.S. Orr⁸, S. Pyatt¹, K. Sato¹¹, C. Solaz⁹, U. Soldevila⁹, J. Thomas¹, M. Ullan⁷, Y. Unno¹⁰

¹*School of Physics and Astronomy, University of Birmingham, Edgbaston, B15 2TT, Birmingham, United Kingdom*

²*Experimental Particle Physics Department, Jožef Stefan Institute, Jamova 39, SI-1000 Ljubljana, Slovenia*

³*Santa Cruz Institute for Particle Physics (SCIPP), University of California, Santa Cruz, CA 95064, USA*

⁴*Academy of Sciences of the Czech Republic, Institute of Physics, Na Slovance 2, 18221 Prague 8, Czech Republic*

⁵*Department of Physics, Simon Fraser University, 8888 University Drive, Burnaby, B.C. V5A 1S6, Canada*

⁶*TRIUMF, 4004 Wesbrook Mall, Vancouver, B.C. V6T 2A3, Canada*

⁷*Centro Nacional de Microelectronica (IMB-CNM, CSIC), Campus UAB-Bellaterra, 08193 Barcelona, Spain*

⁸*Department of Physics, University of Toronto, 60 Saint George St., Toronto, Ontario M5S1A7, Canada*

⁹*Instituto de Física Corpuscular, IFIC/CSIC-UV, C/Catedrático José Beltrán 2, E-46980 Paterna, Valencia, Spain*

¹⁰*Institute of Particle and Nuclear Study, High Energy Accelerator Research Organization (KEK), 1-1 Oho, Tsukuba, Ibaraki 305-0801, Japan*

¹¹*Institute of Pure and Applied Sciences, University of Tsukuba, 1-1-1 Tennodai, Tsukuba, Ibaraki 305-8571, Japan*



ABSTRACT: The successful pre-production delivery of strip sensors for the new Inner Tracker (ITk) for the upgraded ATLAS detector at the High Luminosity LHC at CERN was completed and based on their performance full production has commenced. The overall delivery period is anticipated to last 4 years to complete the approximately 22000 sensors required for the ITk. For Quality Assurance (QA), a number of test structures designed by the collaboration, along with a large area diode and miniature version of the main sensor, are produced in every wafer by the foundry Hamamatsu Photonics K.K (HPK). As well as Quality Control (QC) checks on every main sensor, samples of the QA pieces from each delivery batch are tested both before and after irradiation with results after exposure to neutrons, gammas or protons to fluences and doses corresponding to those anticipated after operation at the HL-LHC to roughly 1.5 times the ultimate integrated luminosity of 4000 fb^{-1} . In this paper the procedures are presented and the studies carried out to establish that the seven ITk QA Strip Sensor irradiation and test sites meet all the requirements to support this very extensive programme throughout the strip sensor production phase for the ITk project.

KEYWORDS: Quality Assurance, Irradiation programme, Strip sensors, ATLAS Inner Tracker.

*Corresponding author, Email: ioannis.kopsalis@stfc.ac.uk

Contents

1. Introduction	1
1.1 Irradiation facilities	1
2. ATLAS18 wafer design	2
3. Measurement setups and qualification methods	3
3.1 ALiBaVa setup	3
3.2 Test chip setup	4
4. Site qualification results	5
4.1 Charge Collection Efficiency	5
4.2 Test chip parameters and monitor diodes	6
5. Summary	8

1. Introduction

Since the Quality Control (QC) testing cannot reliably monitor all the possible variations in production parameters that may influence deterioration during operation at the HL-LHC, the Quality Assurance (QA) procedures including post-irradiation testing, are essential for guaranteeing adequate long term performance and are beyond the scope of what any manufacturer can reasonably check themselves. It is therefore vital that these procedures are as robust as possible and seen by the manufacturer to be fully reliable as they have the potential to lead to rejection of batches otherwise satisfying all the agreed QC tests. As a result ATLAS, with input from independent experts, has developed detailed sensor QA plans, looking at the planned sampling rate; the proposed acceptance criterion; the measurement and irradiation procedures; along with the required standards of precision, consistency and reproducibility, among the participating irradiation facilities and QA institutes [1].

1.1 Irradiation facilities

For a total integrated luminosity of 4000 fb^{-1} , the strip sensors of the ITk detector [2] will be exposed to a large radiation fluence of up to 1.6×10^{15} of $1 \text{ MeV n}_{\text{eq}}/\text{cm}^2$ and ionising dose of 0.66 MGy , including a safety factor of 1.5. The QA silicon pieces are exposed to proton, neutron and gamma irradiation up to the maximum fluences and radiation doses specified for the ITk Strip detector project. The irradiation programme consists of protons of 27 MeV energy at the Birmingham MC40 cyclotron, protons of 70 MeV energy at CYRIC in Tohokou University, neutrons at the Ljubljana JSI TRIGA reactor and gamma rays from the ^{60}Co source at UJP Praha [3]. The samples

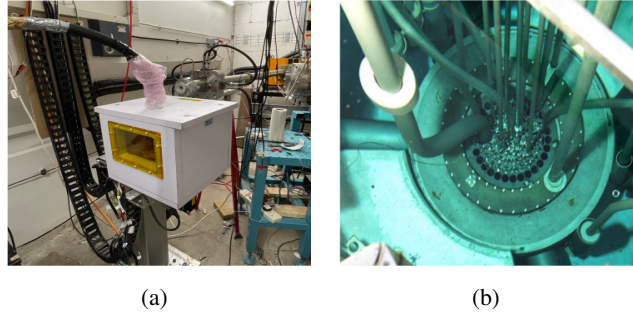


Figure 1. (a) The high intensity proton irradiation area of the Birmingham MC40 cyclotron with the temperature controlled chamber and (b) The core of the TRIGA neutron reactor at JSI, Ljubljana.



Figure 2. The sample holder for the ^{60}Co irradiation at UJP Praha, made with material thickness of 1.5 mm Pb and 1 mm Al to minimise the dose induced from scattered low energy charged particles and to achieve Charge Particle Equilibrium according to Total Ionising Dose Irradiation Standards [4].

remain cold during the proton irradiations. For Birmingham the temperature inside the XY-axis robotic scanning chamber shown in Fig. 1 (a), is -27°C and for CYRIC -15°C . At the timescale of the neutron irradiations at the TRIGA reactor, Fig. 1 (b), no substantial annealing is expected and during the ^{60}Co irradiation at UJP Praha, Fig. 2, the samples are maintained at room temperature.

The beam spot of the MC40 cyclotron configuration is $10\times 10\text{ mm}^2$, and its position is controlled before each irradiation with gafchromic film [5]. Nitrogen gas flow in the chamber ensures the relative humidity during irradiation is $\approx 10\%$. For the QA program during the irradiation site qualification, the scanning operation mode was preferred where the chamber follows a specified path, typically in horizontal rows with a vertical step of 5 mm. The beam current is chosen to be 200 nA. The QA silicon pieces are mounted on a 2 mm thick aluminium plate overlaid with nickel foil for dosimetry, all suspended within the cold box [6].

2. ATLAS18 wafer design

The strip detectors of the outer region of the ITk, at radii (r) $40 < r < 100\text{ cm}$, consist of 4 layers of cylinders (two Short Strip and two Long Strip) and 6 layers of disks with 6 rings of detectors (R0 to R5) in each disk. The ATLAS18 wafer design is laid out and fabricated as the pre-production and production design for the strip sensors for the ITk project [7], as shown in Fig. 3 (a). Large area strip sensors are fabricated in substrate wafers with a diameter of 6 inches in p-type silicon, according to

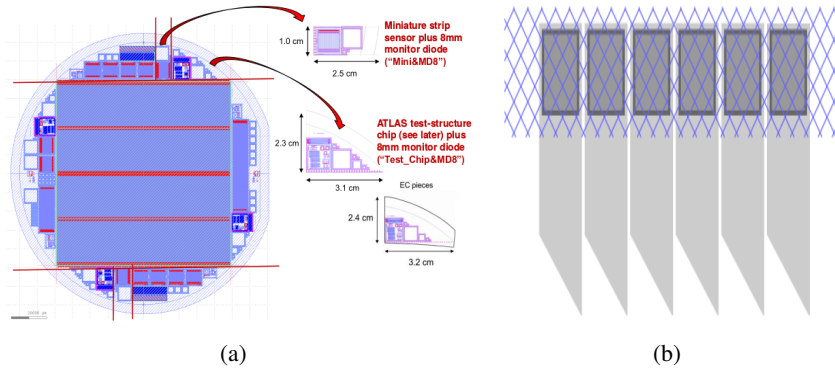


Figure 3. (a) ATLAS18SS design example (out of 8 different layouts) with QA "Mini&MD8" and "Testchip&MD8" wafer pieces. The QA pieces have "similar" geometries in the 8 different wafer layouts. (b) Scanning irradiation pattern of the QA pieces at the Birmingham proton irradiation facility.

the design rules of HPK. This design is the successor to the wafer prototype campaigns ATLAS07, ATLAS12, ATLAS12EC/R0 and ATLAS17LS. The strips are biased via polysilicon resistors and the readout is AC-coupled. The strip pitch is $\approx 75 \mu\text{m}$ in 4 or 2 rows of strip segments. At the peripheral wafer regions, known as "halfmoons" additional test structures are included, miniature sensors, monitor diodes (MD1, MD2, MD4 and MD8 of dimensions 1 mm, 2 mm, 4 mm and 8mm square respectively) and ATLAS test chips. They are used to characterise and validate the sensor key parameters and to monitor the fabrication process of batches produced by HPK, Fig. 3 (b).

3. Measurement setups and qualification methods

3.1 ALiBaVa setup

The charge collection efficiency measurements are performed using the ALiBaVa setup [8], designed to readout multi-channel silicon strip sensors using radiation-hard Beetle chips. The system consists of two hardware boards, a daughterboard on which the Beetle chips and the test mini-sensor are mounted and a motherboard which controls the triggering of signal readout from the sensor and communicates with a control PC, as shown in Fig. 4 (a). The sensor under test is mounted on the daughterboard, biased at high voltage and placed in a freezer beneath a ^{90}Sr radioactive source. A schematic drawing of the KEK, Tsukuba setup is presented in Fig. 4 (b). Two scintillators are placed below the sensor, which trigger the motherboard to readout from the Beetle chip when signal detected from the emitted electrons. The charge collected in each hit, with information of the cluster width and the noise of the strips, it is saved to a binary file. These files are analysed by a programme which extracts the most probable collected charge and saves histograms of the cluster width and noise. Then plots are created of the charge collection efficiency and cluster width as a function of bias voltage. The signal the software receives from the motherboard is measured in ADC counts which results from the Analogue to Digital Conversion of the signal from the Beetle chip. The signal is converted from ADC to a number of electrons. As the gain of the Beetle readout chip is temperature dependent, the signal size in ADC is also temperature dependent, so all signals must be scaled to a common temperature before converted to electrons, e^- . For a pre-irradiated ATLAS mini-strip sensor with $300 \mu\text{m}$ thickness, the signal produced by a minimum

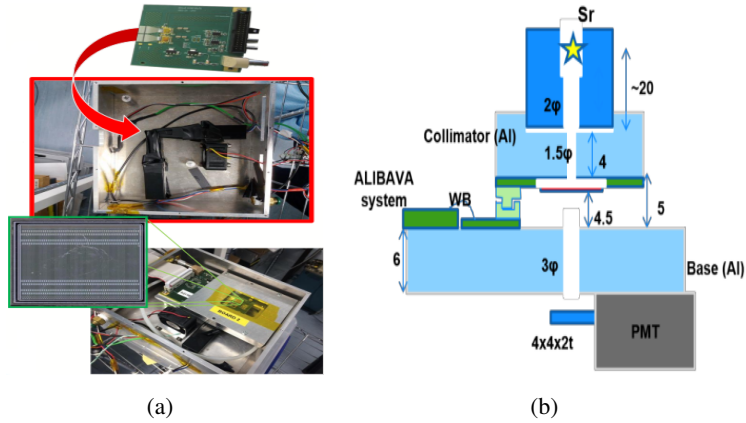


Figure 4. The ALiBaVa setup (a) in Birmingham and (b) in KEK, Tsukuba.

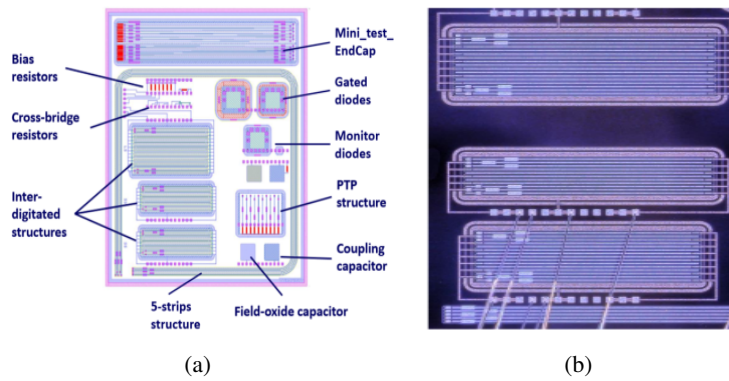


Figure 5. (a) The ATLAS18 test chip wafer piece and (b) The interdigitated structures with the wire-bonding pads.

ionising particle traversing the sensor corresponds to 23.05 ke^- . After irradiation the performance of the sensor is degraded, so the collected charge is significantly lower. The QA specifications after irradiation at $1.6 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$ require a most probable collected charge of at least 6350 e^- at $V_{\text{bias}} = -500 \text{ V}$ [9, 10].

3.2 Test chip setup

The test chip is a $10 \times 12 \text{ mm}^2$ wafer piece featuring numerous structures. Testing of these structures allows the extraction of key parameters of the sensors such as the interstrip resistance and capacitance, the coupling capacitance between implant and readout electrode and the bias resistance. A labelled diagram of the test chip is shown in Fig. 5 (a). The main structures of interest are, the bias resistors for the measurement of bias resistance, the coupling capacitor for the properties of the coupling oxide, the interdigitated structures, Fig. 5 (b), for the interstrip properties, the field-oxide capacitor for the measurement of flatband voltage, the PTP structure for the characterisation of punch-through protection and the cross-bridge resistors for the measurement of implant and metal sheet resistances. The design of the test chip setup developed at Birmingham has been pioneered by collaborators at Toronto, to allow automatic testing of the test chip structures and MD8. A splitting box connects the measurement instruments to two switching matrices which in

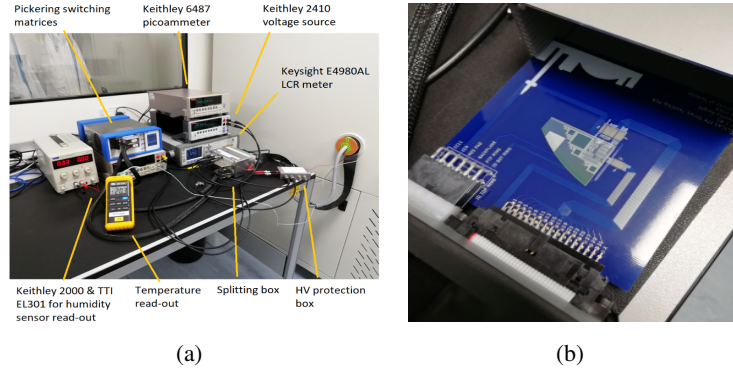


Figure 6. (a) Photo of the Birmingham test chip setup and (b) Test chip mounted on PCB.

turn connect to various channels of the test chip, Fig. 6 (a). The splitting box provides connections between the BNC cables delivering input and output to the instruments and the D-sub connectors of the switching matrices. Also, it connects the D-sub connectors of the switching to the PCB via a Molex and a ribbon cable. Electrical connections to the test chip structures are provided by the available metal pads, which can be wire-bonded to a PCB. The switching matrices allow the connections between each measurement instrument and test chip pad to be switched on and off by a control PC. The wafer piece with the test chip and MD8 is mounted on a PCB which is secured inside a testing box, shown in Fig. 6 (b). The testing box is placed inside a climate chamber which maintains stable temperature during measurements and allows for testing at -20°C . During the site qualification process, Python scripts were prepared to control through a PC, the measurement instruments along with the switching matrices and record the measured data.

4. Site qualification results

4.1 Charge Collection Efficiency

The most probable charge collected by the sensor, is extracted by a binned likelihood fit performed to the distribution of the collected charge per trigger event. In particular, the Landau distribution is convoluted with a Gaussian distribution and the convolution result is used to fit the charge collection histograms. The fit presented in Fig. 7 (a), has three floating parameters, the most probable value (MPV), the width of the Landau distribution and the width of the Gaussian. The mean of the Gaussian is fixed to zero. The fitting range is carefully selected, so the signal peak can be separated from the noise tail which is present at low ADC counts.

The site qualification parameters of the QA groups on CCE measurements, are presented in table 1, after neutron irradiation at target fluence $1.6 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$. The MPV of the Landau component is used for the charge signal amplitude, as the difference with the MPV of the convolution has been investigated and found to be negligible. Good agreement is observed between the CCE values for the different sites. The samples shipped to the testing sites were irradiated at the same irradiation slot, so the usual fluence uncertainty of the order of 10%, associated with the irradiations did not contribute in this comparison. The collected charge as a function of voltage after proton irradiation at target fluence $1.6 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$ at CYRIC and Birmingham cyclotron facility is presented in Fig. 7 (b). The comparison between pre- and post-annealing has been performed during

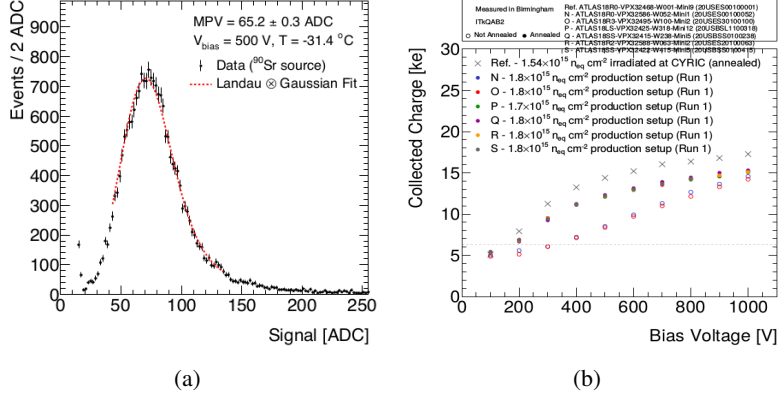


Figure 7. (a) Charge collection histogram for an ATLAS mini-sensor with Landau-Gaussian convolution fit and (b) Charge collection as a function of bias voltage after proton irradiation of six ATLAS18 pre-production mini-sensors pre- and post-annealing irradiated within the same irradiation slot at the Birmingham cyclotron facility.

the Birmingham irradiation site verification process and the post-annealing results are compared to CYRIC. The collected charge measured at 500 V negative bias voltage verifies the QA requirement of at least $6350 e^-$.

Table 1. Site qualification parameters for CCE measurements.

	Birmingham	Ljubljana	Toronto	Tsukuba	Valencia
Signal at 500 V [ke^-]	7.18	7.48	7.46	7.71	7.63
Signal at 700 V [ke^-]	9.68	10.14	10.37	10.11	10.55
Noise at 500 V [ke^-] (irrad)	0.94	0.68	0.52	1.17	0.68
Noise at 700 V [ke^-] (irrad)	0.94	0.70	0.55	1.18	0.70
Cluster width at 500 V (irrad)	1.32	1.38	1.30	1.11	1.89
Cluster width at 700 V (irrad)	1.42	1.50	1.40	1.25	2.14
Current at 500 V [μA] (scaled to $-20^\circ C$)	17.80	16.20	13.30	16.70	16.60

4.2 Test chip parameters and monitor diodes

For monitoring the wafer quality and process fabrication, current-voltage and capacitance-voltage measurements are performed on pre-irradiated MD8 monitor diodes part of the QA pieces ("Mini&MD8" and "Testchip&MD8"). In Fig. 8 (a) is presented the current-voltage of MD8s measured on an automatic probe station in an ambient environment, relative humidity $RH > 25\%$ and temperature $20^\circ C$. The total current for all the cases is $< 0.1 \mu A/cm^2$. In the QA procedures, the breakdown voltage V_{bd} is specified to be above 500 V for dry environment $RH < 10\%$. For devices tested in ambient environment, a few cases with $V_{bd} < 500$ V are observed. The full depletion voltage V_{fd} , extracted pre-irradiation for all the pre-production batches is presented in Fig. 8 (b), according to the QA specifications below 350 V.

For verification purposes testing sites performed measurements in one pre-irradiated and one gamma irradiated at 0.66 MGy test chip, after annealing of 80 minutes at $60^\circ C$. The bias resistor R_{bias} structures, are identical to those on the main sensor which provide a high resistance electrical connection between the bias rail and the strip implants [11]. The R_{bias} is extracted from the

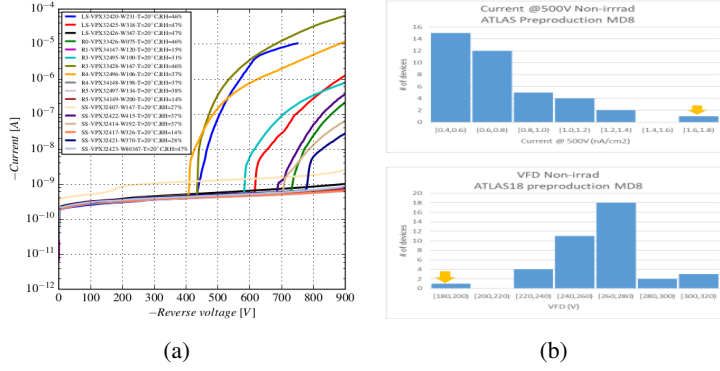


Figure 8. ATLAS18 pre-production (a) MD8 current as a function of voltage and (b) Full depletion voltage results.

current as a function of voltage measurement. For the pre-irradiated chips R_{bias} is extracted with average values of $1.55 \text{ M}\Omega$. After gamma irradiation all of the three resistors tested with R_{bias} average of $2.16 \text{ M}\Omega$, the measurements performed at -20°C [11]. In Fig. 9 (a) the current as a function of voltage measurements of the bias resistor structures on the site verification test chips (one pre-irradiated, one gamma irradiated) is presented. The blue band shows the acceptance range $R_{\text{bias}} = 1.5 \pm 0.5 \text{ M}\Omega$. The test chip features a punch-through protection (PTP) structure, consisting of the end of ten implants surrounded by a bias rail, to which they are connected at one end by a bias resistor, and a guard ring. Testing this structure involves applying a voltage to individual implants and measuring the current between the implant and the bias rail, while the backplane of the sensor is held at a high negative voltage to bias the Si bulk. From the gradient of the current as a function of voltage curve, the effective resistance is presented as a function of voltage, Fig. 9 (b). The voltage at which the effective resistance is half of that of the bias resistor, is considered as the punch-through protection voltage, V_{ptp} . To ensure the protection of the readout electronics, the V_{ptp} is required to be significantly lower than the breakdown voltage of the coupling capacitor. The parametric test setup can be used to extract V_{ptp} for five of the ten channel ends on each test chip. For the pre-irradiated site verification test chip, an average value of $V_{\text{ptp}} = 13.81 \text{ V}$ is measured with a range of 0.05 V between individual implant ends. For the gamma irradiated sample, a lower average punch-through voltage of 10.66 V is measured with a range of 0.19 V . Both pre- and post-irradiation, V_{ptp} is measured below 100 V , the voltage limit to which the coupling capacitor is tested for dielectric breakdown. The interdigitated structures are designed to perform interstrip resistance R_{int} , and interstrip capacitance C_{int} , measurements. It consists of a series of n^+ implants of which every odd implant is connected at one side, and every even strip at the other so the total strip length is equal to that in the main sensors. The strips are surrounded by a bias ring, to which they are not connected and a guard ring [12]. There are three interdigitated structures on each test chip with different strip lengths and angles corresponding to main sensors for different parts of the strip detector. For the R_{int} measurement the bulk of the chip is fully depleted and the bias ring is grounded. A voltage sweep from -5 to 5 V is applied to one set of strips while the current is measured at the other set. The R_{int} is extracted from the inverse slope of the current-voltage curve. According to the QA specifications, the R_{int} is required to be a factor of 10 greater than the bias resistance to ensure good isolation between neighbouring implants. In Fig. 10 (a) the current as

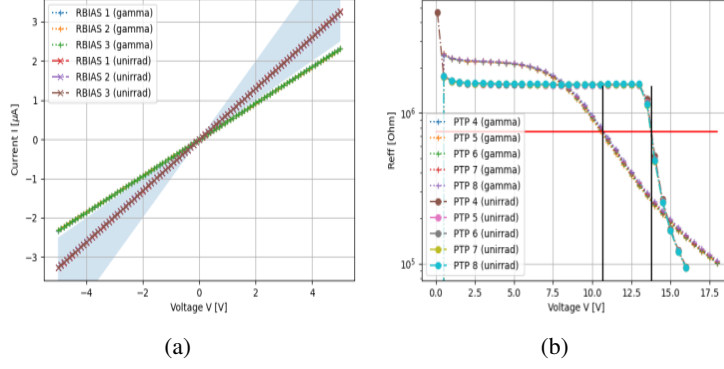


Figure 9. ATLAS18 pre-production (a) Polysilicon bias resistors current as a function of voltage. The blue band shows the specification of $R_{\text{bias}} = 1.5 \pm 0.5 \text{ M}\Omega$. (b) Punch-through-protection effective resistance as a function of voltage, before and after gamma irradiation.

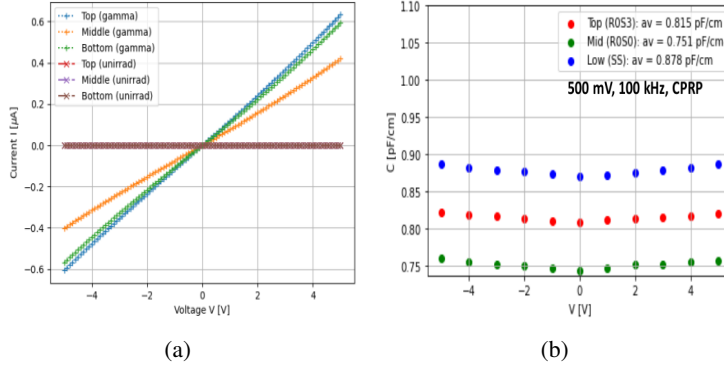


Figure 10. ATLAS18 pre-production (a) Interstrip resistance as a function of voltage, before and after gamma irradiation and (b) Interstrip capacitance as a function of voltage after gamma irradiation.

a function of voltage measurements of interdigitated structures on the site verification test chips (one pre-irradiated, one gamma irradiated) is presented. The current value for the pre-irradiated structure is a few pA, as opposed to the few hundred nA after gamma irradiation due to decreased interstrip resistance. For the interstrip capacitance C_{int} measurement, Fig. 10 (b), the Si-bulk is biased in full depletion and the bias ring is grounded. The same voltage sweep as in the R_{int} measurement, is applied to one set of strips with the low LCR meter probe to the second set. The C_{int} is defined as the capacitance contribution from both neighbouring strips $C_{\text{int}} = C_{\text{meas}}/l_{\text{strip}}$, where l_{strip} is the total strip length. The C_{int} is required to be measured less than 1 pF/cm, motivated by its impact on the module readout noise, as well as prevention of signal loss due to charge division with C_{coupl} . The above QA requirement is satisfied for the gamma irradiated test chip. After completion of the site qualification procedures, proton irradiated pre-production test chips at target fluences 5×10^{14} and $1.6 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$ are measured. The extracted parameters are presented in table 2.

5. Summary

The seven QA testing sites (Birmingham, Barcelona, Ljubljana, Prague, Toronto, Tsukuba and

Table 2. Test chip parameters and monitor diode after proton irradiation at CYRIC.

Batch	VPX32469-W001	VPX32469-W095
Type	ATLAS18R1	ATLAS18LS
Serial Number	20USES11700001	20USBSL1700095
Irradiation	p4.68E14(CYRIC)	p1.54E15(CYRIC)
MD8		
Norm. Current [A/cm ²]	8.98×10^{-6}	2.51×10^{-5}
V _{bd} [V]	-	-
V _{fd} [V]	no meas	no meas
Bias Resistors		
Average R _{bias} [Ohm]	1.75×10^6	1.81×10^6
Range R _{bias} [Ohm]	5.39×10^3	6.71×10^3
Coupling Capacitor		
C _{coupl} [pF/cm]	20.8	21.1
I _{coupl} at 500 V [A]	1.50×10^{-9}	1.50×10^{-9}
Interdigitated Structure - Low		
R _{int} [Ohm]	6.07×10^7	1.54×10^7
C _{int} [pF/cm]	1.36	1.59
Interdigitated Structure - Mid		
R _{int} [Ohm]	2.91×10^7	no meas
C _{int} [pF/cm]	1.70	no meas
Interdigitated Structure - Up		
R _{int} [Ohm]	3.44×10^7	2.67×10^6
C _{int} [pF/cm]	1.25	0.89
PTP Structure		
Average V _{ptp} [V]	35.20	26.83
Range V _{ptp} [V]	0.87	0.42

Valencia) have been qualified. Agreement is observed between the test sites of the measured CCE at 500 V with samples from the same irradiation slot. In addition all sites confirm uniformity of the extracted test chip parameters after gamma irradiation. During pre-production, in total 39 batches were received and all qualified. Furthermore, the irradiation plan for the production sensors was established. The qualification of the Birmingham irradiation site required further investigation after the Production Readiness Review against intermittent mini-sensor low CCE performance. The site finally qualified after having established consistent results internally to the site and with other irradiation sites.

Acknowledgments

The authors acknowledge, the Particle Physics Consolidated Grants received from the UK Research and Innovation - STFC Grants. ST/N000463/1, ST/N001125/1, ST/P005888/1, the US Department of Energy - Grant DE-SC0010107, the Canada Foundation for Innovation, the Natural Science and Engineering Research Council, the Ministry of Education of the Czech Republic projects LTT17018 Inter-Excellence and LM2018104 CERN-CZ and the Charles University grant GAUK 942119, the support from the Slovenian Research Agency (research core funding No. P1 0135) and the Spanish R&D grant PID2019-110189RB-C22, funded by MCIN/ AEI/10.13039/501100011033.

References

- [1] M. Ullán, et al., *Quality Assurance methodology for the ATLAS Inner Tracker strip sensor production*, Nucl. Inst. Meth. A, 981, (2020) 164521, <https://doi.org/10.1016/j.nima.2020.164521>.
- [2] The ATLAS Collaboration, *Technical Design Report for the ATLAS Inner Tracker Strip Detector*, <https://cds.cern.ch/record/2257755/files/ATLAS-TDR-025pdf>.
- [3] M. Mikestikova, et al., *Electrical characterization of surface properties of the ATLAS17LS sensors after neutron, proton and gamma irradiation*, Nucl. Inst. Meth. A, 983, (2020) 164456, <https://doi.org/10.1016/j.nima.2020.164456>.
- [4] Standard Practice for Minimizing Dosimetry Errors in Radiation Hardness Testing of Silicon Electronic Devices Using Co-60 Sources, ASTM E1249, (2000)
- [5] P. Allport, et al., *Recent results and experience with the Birmingham MC40 irradiation facility*, J. Instrum. 12, (2017), C03075, <https://iopscience.iop.org/article/10.1088/1748-0221/12/03/C03075>.
- [6] P. Allport, et al., *Experimental determination of proton hardness factors at several irradiation facilities*, J. Instrum. 14, (2019), P12004, <https://doi.org/10.1088/1748-0221/14/12/P12004>.
- [7] Y. Unno, et al., *Specifications and Pre-production of n^+ -in-p Large-format Strip Sensors fabricated in 6-inch Silicon Wafers, ATLAS18, for Inner Tracker of ATLAS Detector for High-Luminosity Large Hadron Collider*, J. Instrum. (2022), submitted for publication.
- [8] ALiBaVa Systems, 2022, <https://alibavasystems.com/>.
- [9] K. Hara, et al., *Charge collection study with the ATLAS ITk prototype silicon strip sensors ATLAS17LS*, Nucl. Inst. Meth. A, 983, (2020) 164422, <https://doi.org/10.1016/j.nima.2020.164422>.
- [10] K. Hara, et al., *Charge collection and field profile studies of heavily irradiated strip sensors for the ATLAS inner tracker upgrade*, Nucl. Inst. Meth. A, 831, (2016) 181-188, <http://dx.doi.org/10.1016/j.nima.2016.04.035>.
- [11] V. Latoňová, et al., *Characterization of the Polysilicon Resistor in Silicon Strip Sensors for ATLAS Inner Tracker as a Function of Temperature, Pre- And Post-Irradiation*, Nucl. Inst. Meth. A (2022), submitted for publication.
- [12] P. Allport, et al., *Pre-Production Results from ATLAS ITk Strip Sensors Quality Assurance Testchip*, J. Instrum. (2021), accepted for publication.